

Circuit Board Fabrication Notes

- 1. Fabricate per IPC-6011 and IPC6012. Inspect to IPA-A-600 Class 2 or updated standard.**
- 2. Printed Circuit Board is defined by files listed in files set.**
- 3. Modification to copper within the PCB outline is not allowed without permission, except where noted otherwise. The manufacturer may make adjustments to compensate for manufacturing process, but the final PCB is required to reflect the associated gerber file design ± 0.001 in. for etched features within the PCB outline.**
- 4. Material in accordance with IPC-4101/21, FR4, Tg 125° C min.**
- 5. Layer to layer registration shall not exceed ± 0.004 in.**
- 6. External finished copper conductor thickness shall be 0.0026 in. min. (i.e. 2oz)**
- 7. Copper plating thickness for through holes shall be 0.0013 in. min. (i.e. 1oz)**
- 8. All holes sizes are finished hole size.**
- 9. Finished PCB thickness 0.062 in.**
- 10. All undimensioned holes to be drilled using the NC drill data.**
- 11. Size tolerance of plated holes: ± 0.003 in. : non-plated holes ± 0.002 in.**
- 12. All holes shall be ± 0.003 in. of their true position U.D.S.**
- 13. Construction to be SMOBC, using liquid photo image (LPI) solder mask in accordance with IPC-SM-B40C, Type B, Class 2, and be green in color.**
- 14. Solder mask misregistration ± 0.004 in. max.**
- 15. Silkscreen shall be permanent non-conductive white ink.**
- 16. The fabrication process shall be UL approved and the PCB shall have a flammability rating of UL94V0 to be marked on the solder side in silkscreen with date, manufacturer's approved logo, and type designation.**
- 17. Warp and twist of the PCB shall not exceed 0.0075 in. per in.**
- 18. 100% electrical verification required.**
- 19. Surface finish: electroless nickel immersion gold (ENIG)**
- 20. RoHS 2002/95/EC compliance required.**